

BRIEF STATEMENTS UNDER ARTICLE 19(1)

Claims 1, 5 and 9 have been amended to clarify that “the equipotential wiring which is a short-circuit conductive pattern is prevented from being directly sandwiched between the insulating substrate and the semiconductor substrate”. Note that this amendment does not exclude e.g. that in FIG. 1 of the present application, the equipotential wiring is sandwiched between the insulating substrate and the semiconductor substrate via the conductive film 9a.

None of the Cited Documents 1, 2 show the equipotential wiring to be thus formed.

As described in the specification, according to the present invention, it is possible to obtain an effect, which cannot be obtained by the Cited References 1, 2, that “a short-circuit conductive pattern is prevented from being sandwiched between the substrates, thereby preventing bonding voids from occurring”.